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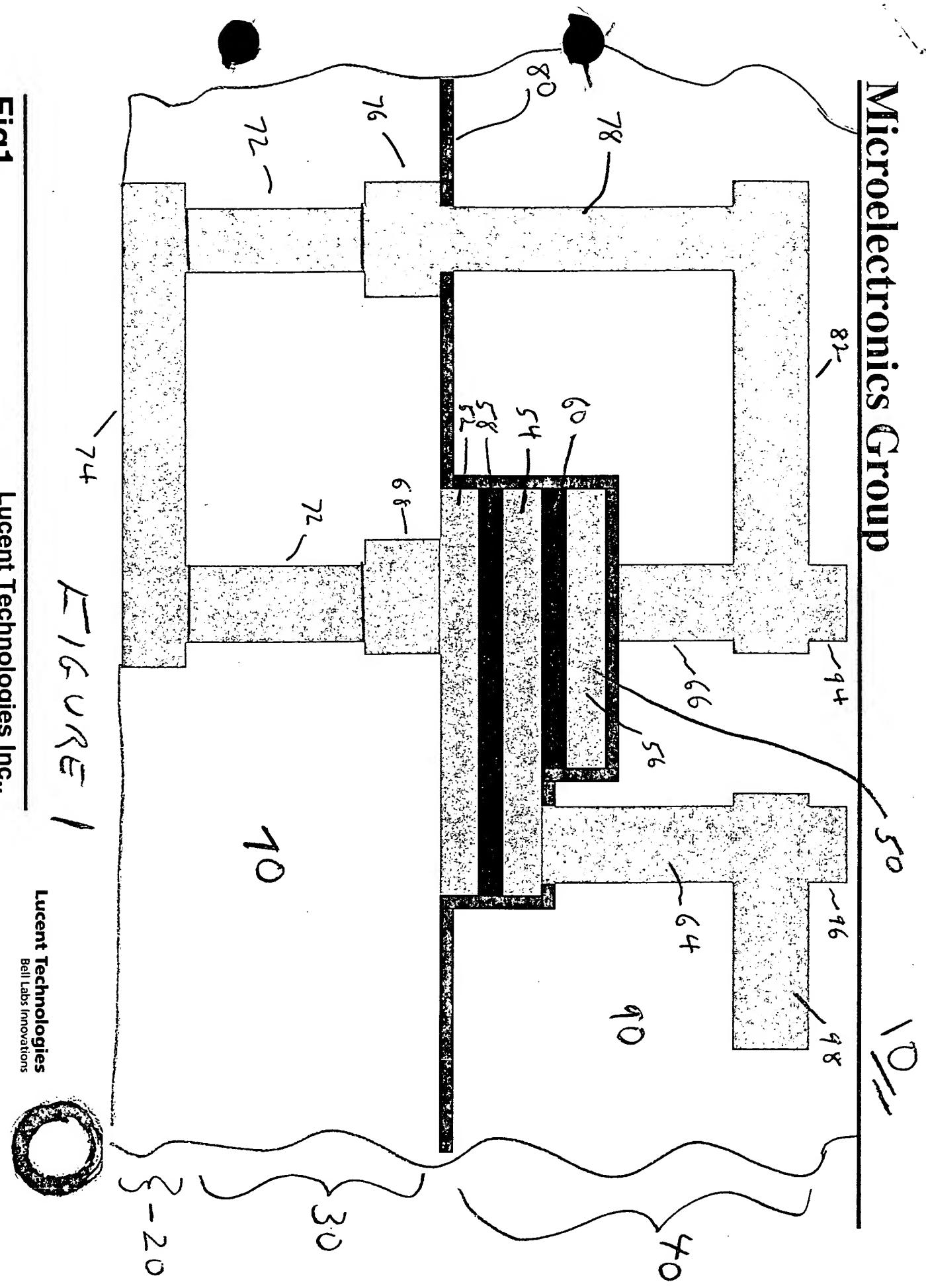


Fig1

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Bell Labs Innovations

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2. Cu3 CMP

3. Metals and MOM oxide deposition

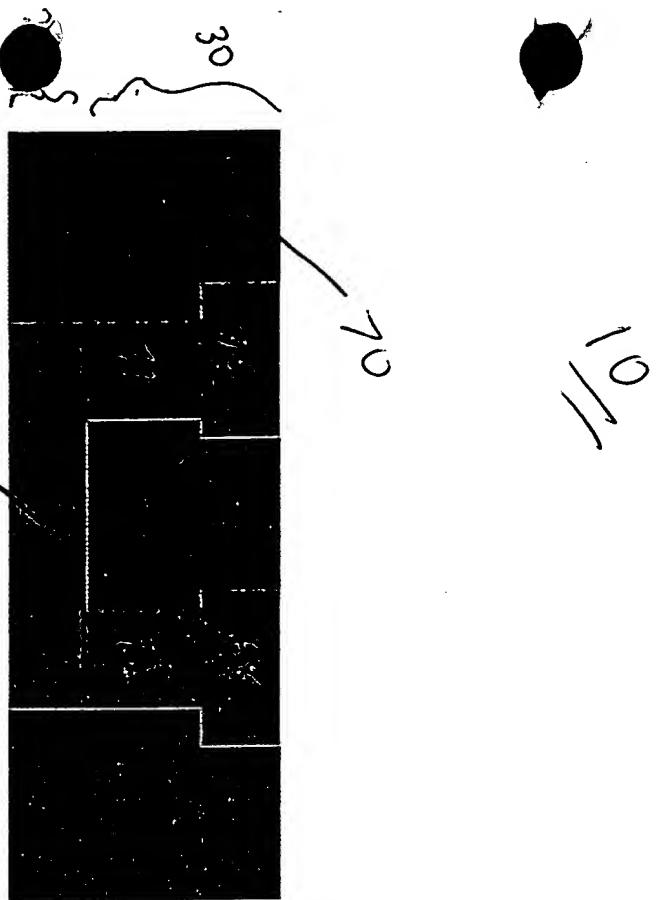


FIGURE 2

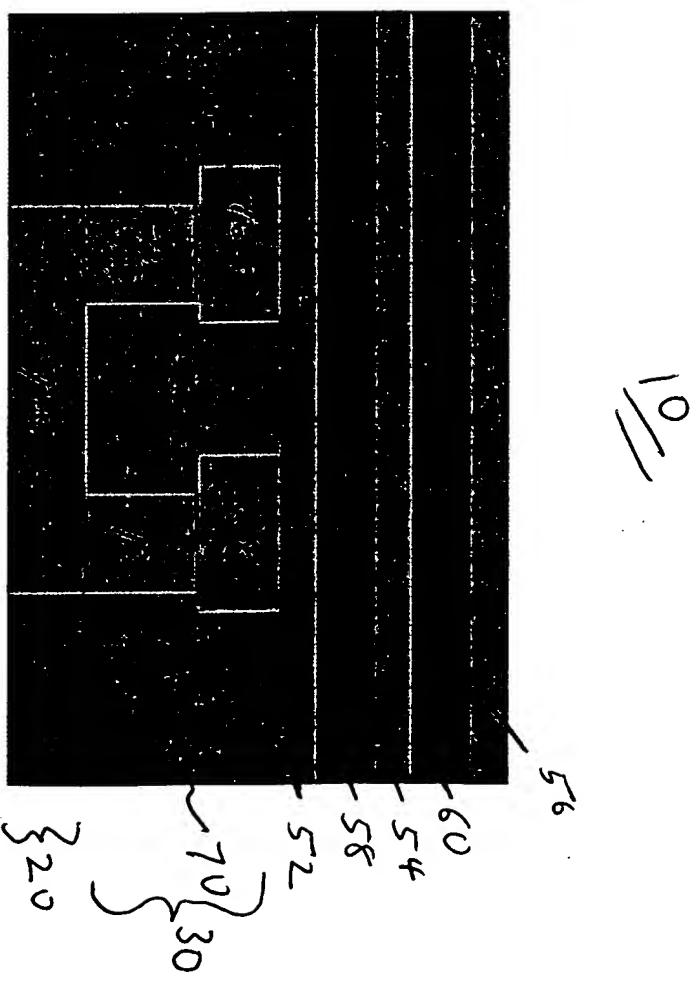


FIGURE 3

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Fig. 2&3

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4. Notch etch for contact to metal B

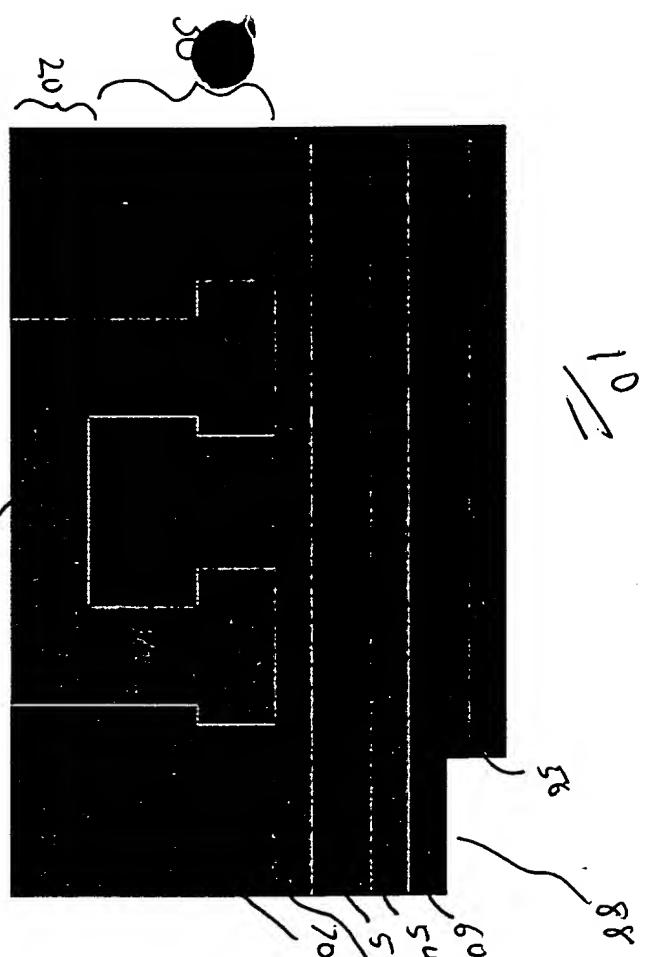


FIGURE 4

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5. Metal and oxide etch

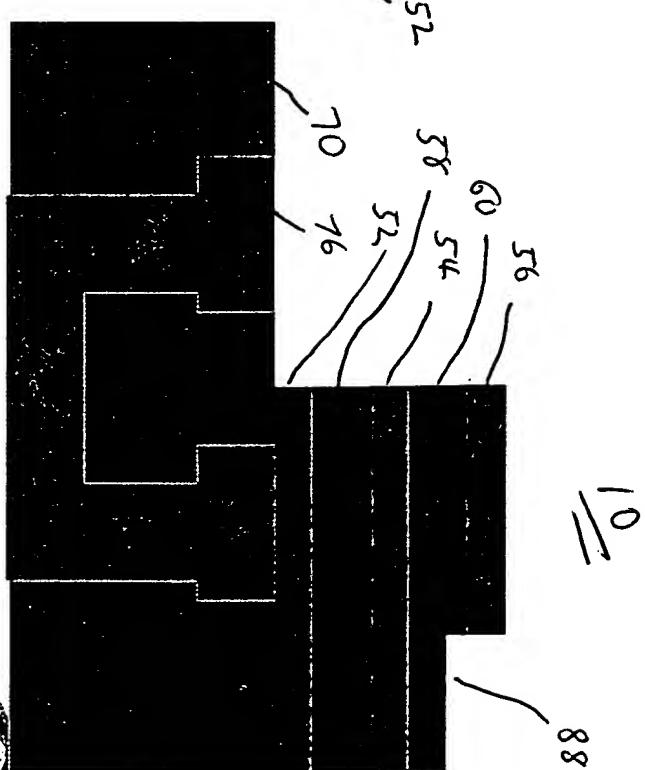


FIGURE 5

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Fig. 4&5

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6. SiN<sub>4</sub> and dielectric 4 deposition

7. Dielectric 4 CMP

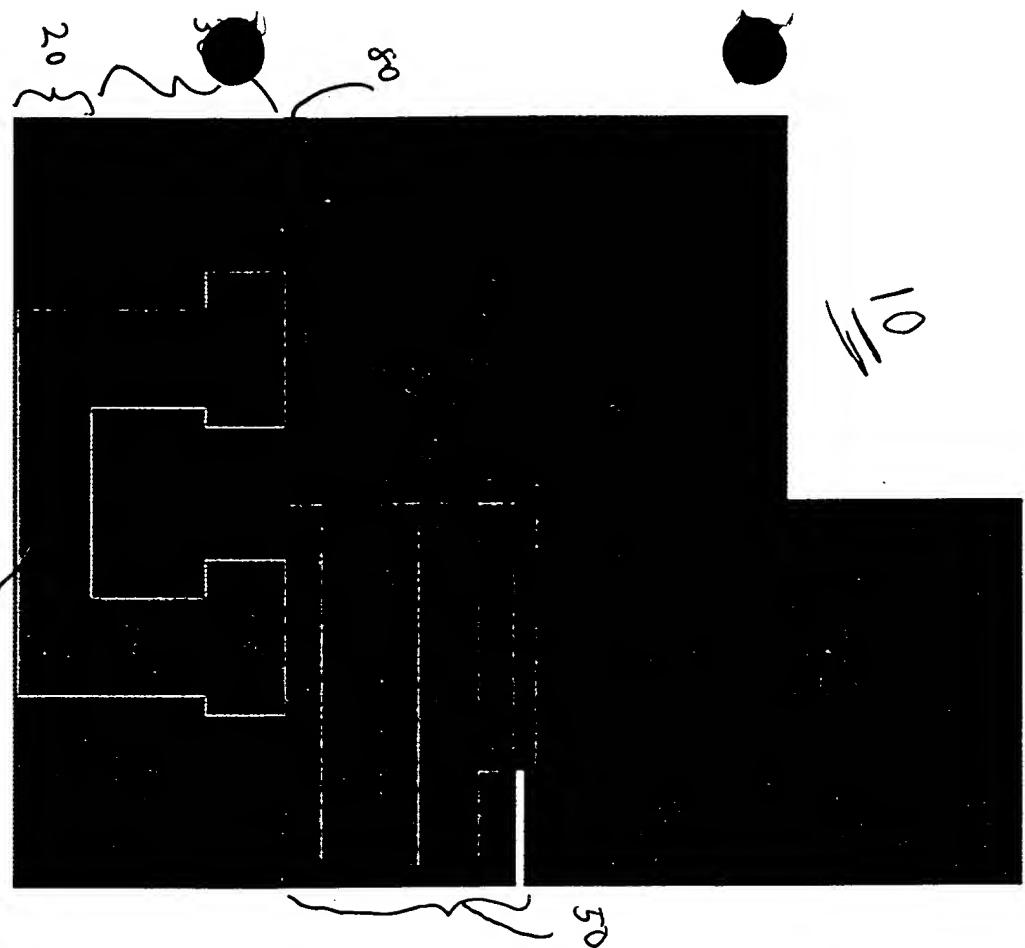
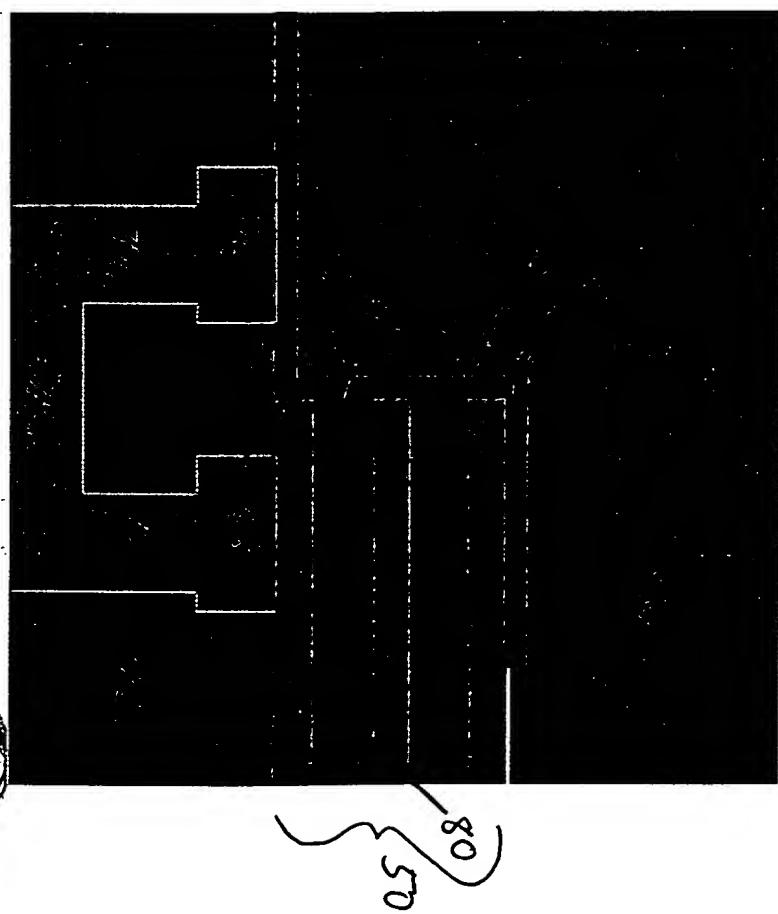


Figure 6  
74



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Fig.6&7

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8. Another version of doublemom

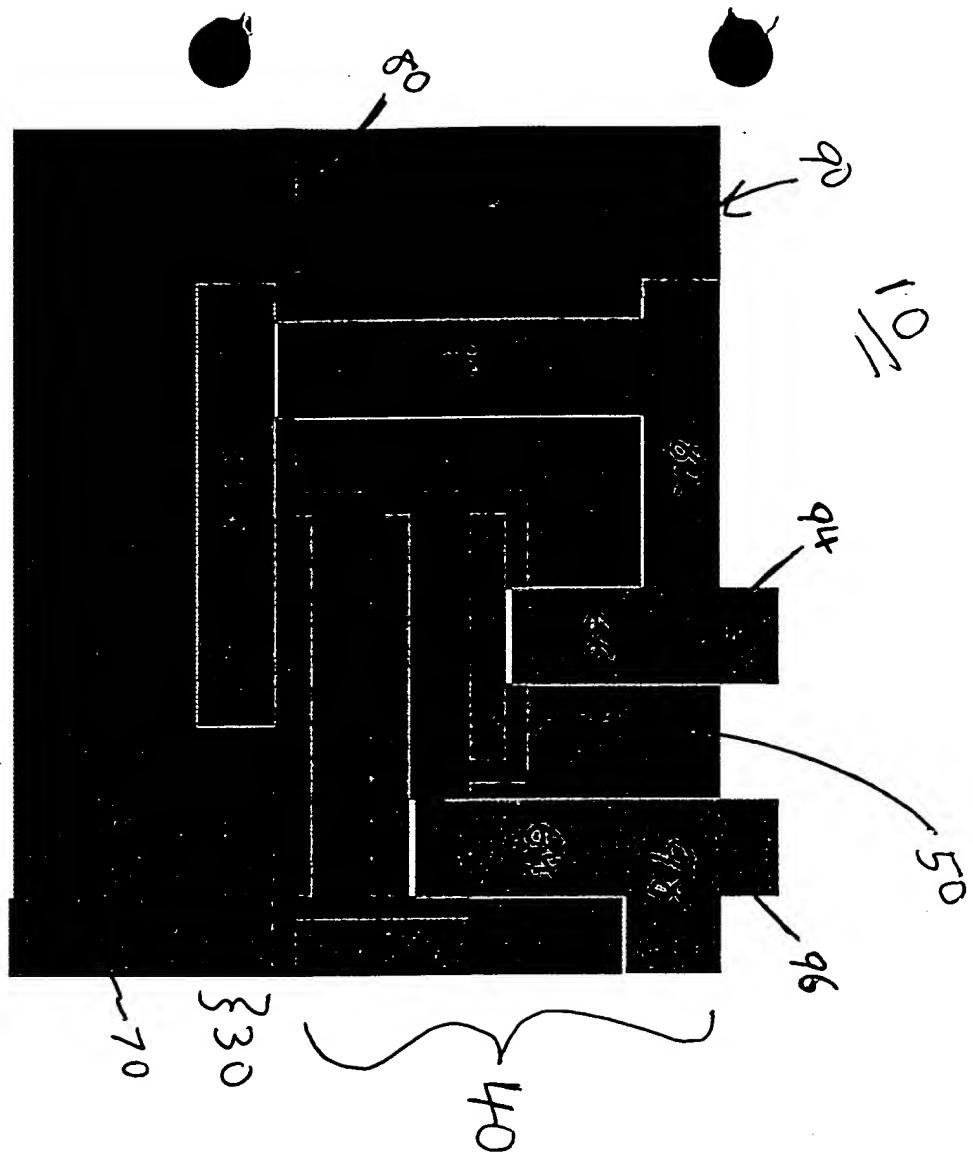


Figure 8

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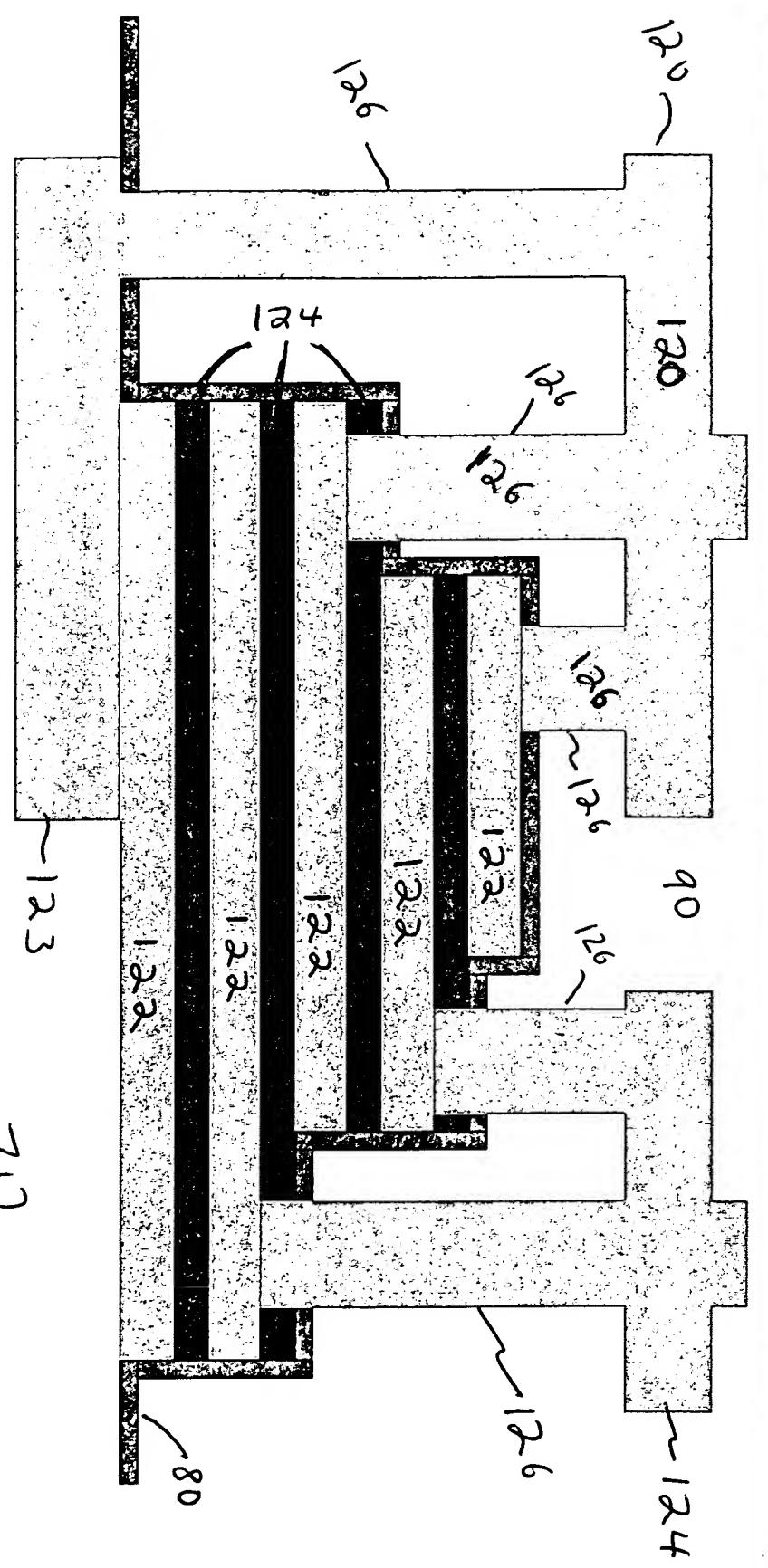
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Fig. 9

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## FIGURE 9



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Figure 10  
250

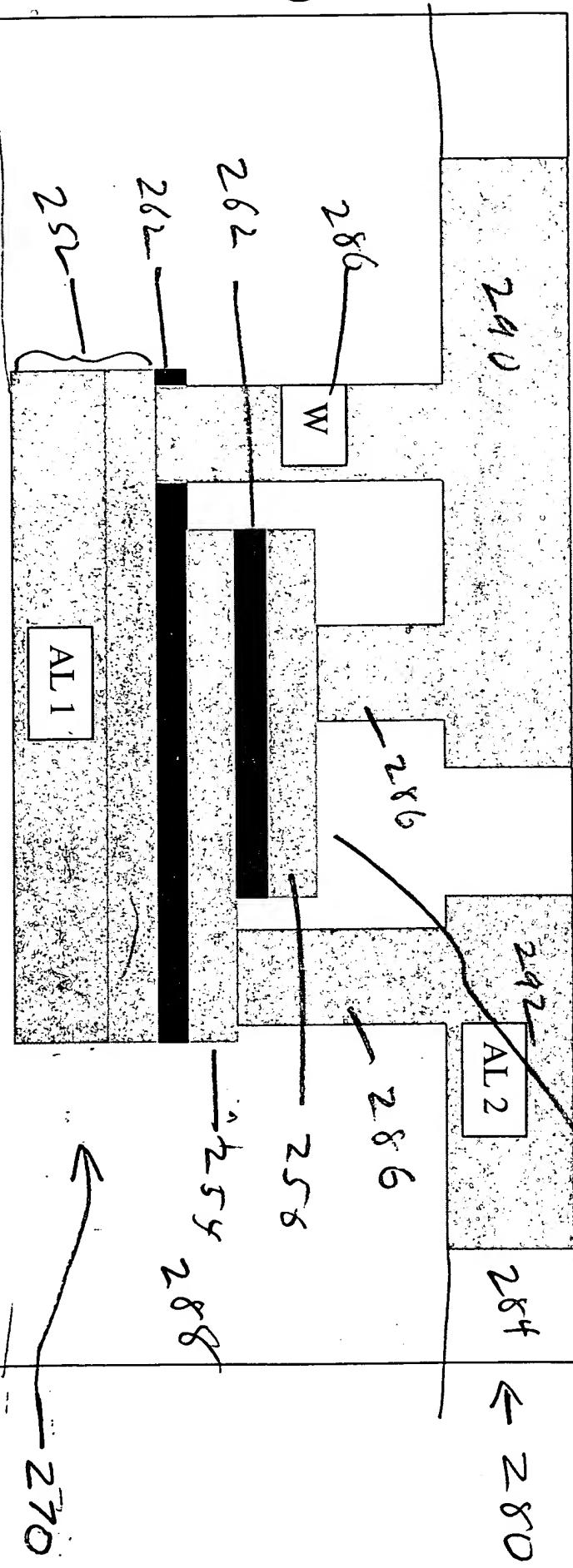


Figure 10

Figure 10  
250

Winston Yan

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